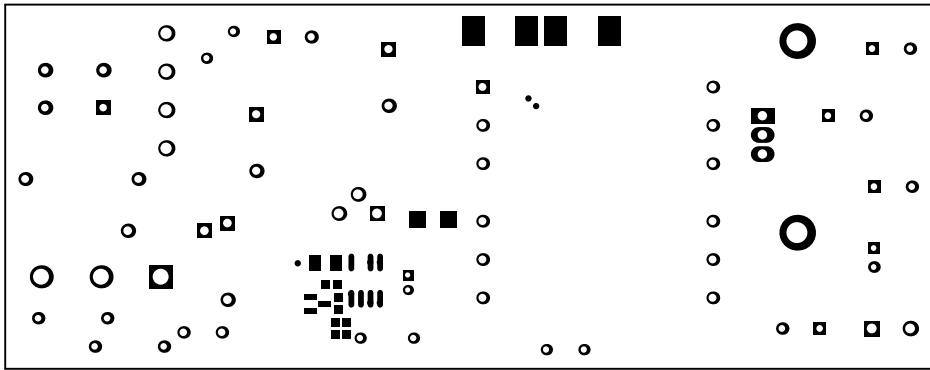
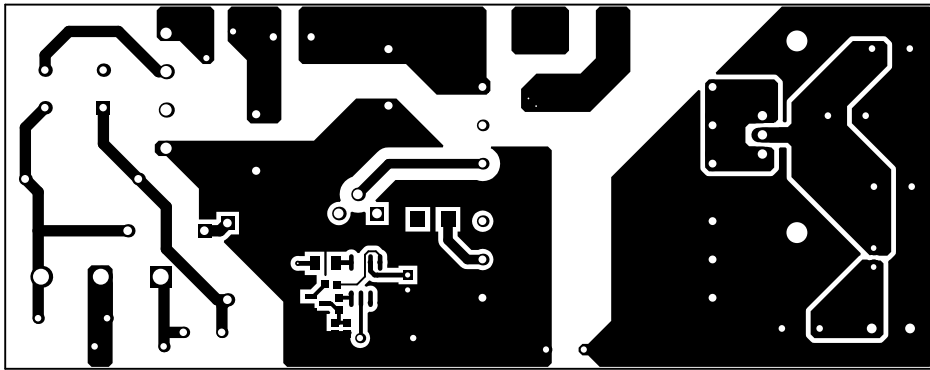


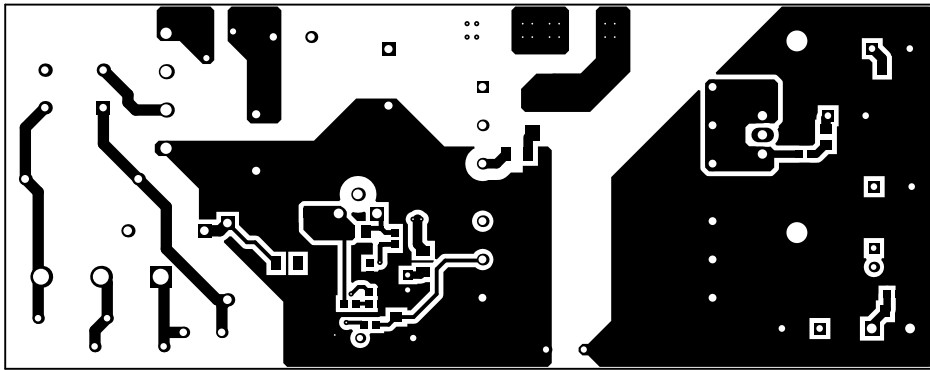
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10335	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay			
PLOT NAME = Top Overlay	GENERATED : 11/7/2014 9:38:50 AM	TEXAS INSTRUMENTS	



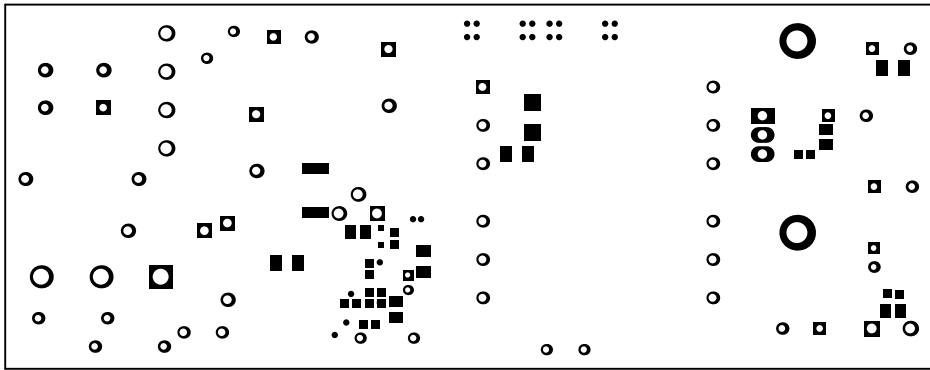
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LAYER NAME = Top Solder			
PLOT NAME = Top Solder Mask	GENERATED : 11/7/2014 9:38:51 AM	TEXAS INSTRUMENTS	



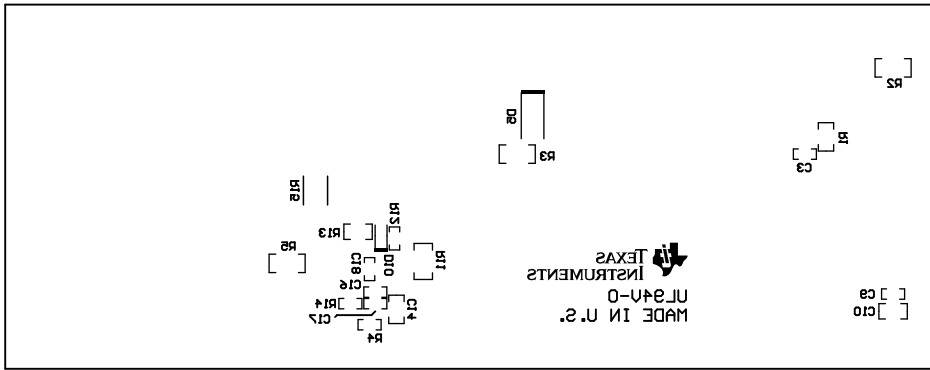
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LAYER NAME = Top Layer			
PLOT NAME = Top Layer	GENERATED : 11/7/2014 9:38:51 AM	TEXAS INSTRUMENTS	



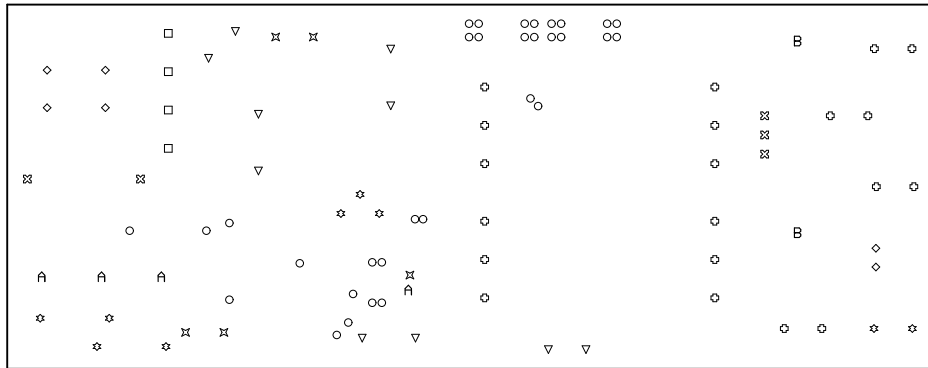
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LAYER NAME = Bottom Layer			
PLOT NAME = Bottom Layer	GENERATED : 11/7/2014 9:38:52 AM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10335	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder			
PLOT NAME = Bottom Solder Mask	GENERATED : 11/7/2014 9:38:52 AM	TEXAS INSTRUMENTS	



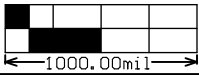
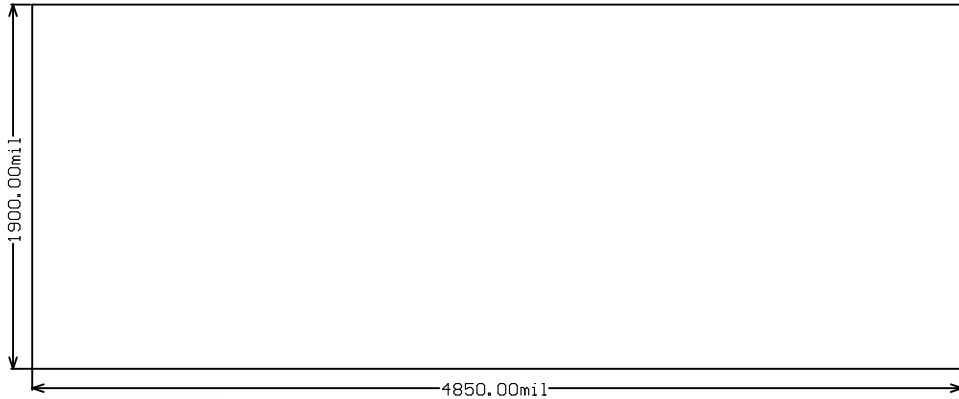
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10335	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay			
PLOT NAME = Bottom Overlay	GENERATED : 11/7/2014 9:38:53 AM	TEXAS INSTRUMENTS	



Symbol	Hit Count	Tool Size	Plated	Hole Type
○	28	10mil (0.254mm)	PTH	Round
⊗	1	28mil (0.711mm)	PTH	Round
A	1	28.012mil (0.712mm)	PTH	Round
◇	2	31mil (0.787mm)	PTH	Round
▽	6	33.465mil (0.85mm)	PTH	Round
*	4	35mil (0.889mm)	PTH	Round
⊙	8	35.433mil (0.9mm)	PTH	Round
⊗	4	39.37mil (1mm)	PTH	Round
◇	4	40mil (1.016mm)	PTH	Round
⊙	12	41.339mil (1.05mm)	PTH	Round
⊗	2	42.079mil (1.069mm)	PTH	Round
▽	4	43.307mil (1.1mm)	PTH	Round
○	4	45.276mil (1.15mm)	PTH	Round
⊗	3	50mil (1.27mm)	PTH	Round
*	5	51.181mil (1.3mm)	PTH	Round
□	4	59.055mil (1.5mm)	PTH	Round
A	3	84.646mil (2.15mm)	PTH	Round
B	2	110.236mil (2.8mm)	PTH	Round
	97 Total			

Drill Table

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10335	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing			
PLOT NAME = Drill Drawing	GENERATED : 11/7/2014 9:38:53 AM	TEXAS INSTRUMENTS	



1000.00mil

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10335	REV: B	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions			
PLOT NAME = Board Dimensions	GENERATED : 11/7/2014 9:38:54 AM	TEXAS INSTRUMENTS	

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